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ABSTRACT

A pressure-sensitive adhesive tape (2) is adhered to a leadframe (1). A semiconductor chip (3) is bonded to the leadframe (A) having the pressure-sensitive adhesive tape and encapsulated with a resin in a mold (4). The pressure-sensitive adhesive tape (2) is stripped after the encapsulating. The resin encapsulating efficiency is improved, and breakage of bonding parts is prevented with certainty.



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